

## N-Channel Enhancement Mode Field Effect Transistor

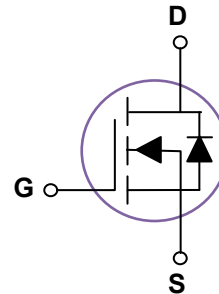
### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

$V_{DS}$	80V
$I_D$ (at $V_{GS}=10V$ )	100A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	3.2m $\Omega$ (Typ)

PDFN5x6



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	$V_{DS}$	80	V	
Gate-Source Voltage	$V_{GS}$	+20/-12	V	
Drain Current-Continuous	TC=25 $^\circ C$	$I_D$	100	A
	TC=100 $^\circ C$	$I_D$	63	A
Maximum Power Dissipation	$P_D$	142	W	
Single pulse avalanche energy <sup>(1)</sup>	$E_{AS}$	540	mJ	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$	

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		1.1	$^\circ C / W$
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		62	$^\circ C / W$

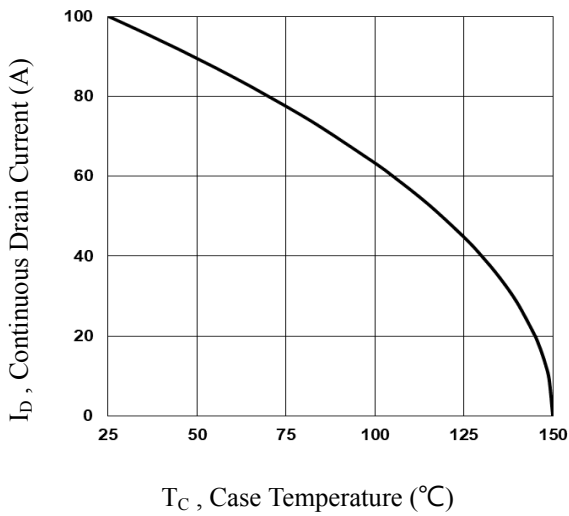
**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	80			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=80V, V_{GS}=0V$			1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=20V, V_{DS}=0V$			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.6	2.5	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=20A$		3.2	3.9	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$		4.5	6.0	m $\Omega$
<b>DYNAMIC PARAMETERS</b>						
$C_{ISS}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V,$ $F=1.0MHz$		5160		pF
$C_{OSS}$	Output Capacitance			1346		pF
$C_{RSS}$	Reverse Transfer Capacitance			40		pF
<b>SWITCHING PARAMETERS</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=40V, I_D=1A,$ $V_{GS}=10V,$ $R_G=6\Omega$		20		nS
$t_r$	Turn-on Rise Time			13		nS
$t_{d(off)}$	Turn-Off Delay Time			36		nS
$t_f$	Turn-Off Fall Time			18		nS
$Q_g$	Total Gate Charge	$V_{DS}=40V, I_D=10A,$ $V_{GS}=10V$		88		nC
$Q_{gs}$	Gate-Source Charge			10.2		nC
$Q_{gd}$	Gate-Drain Charge			24		nC
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_{SD}=10A$		0.72	1.2	V
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V,$ $F=1MHz$		1.65		$\Omega$

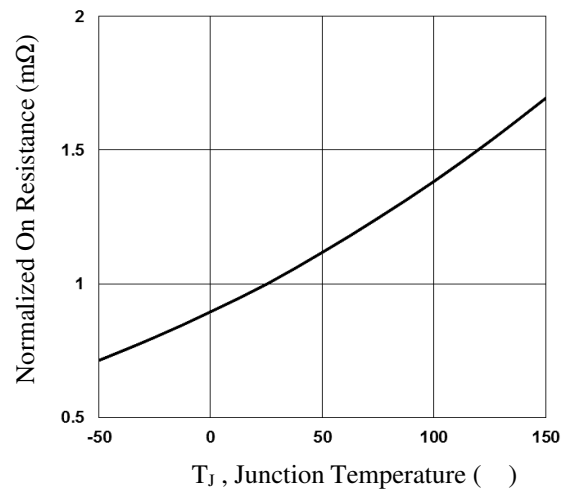
Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=95A.$ , Starting T<sub>J</sub>=25°C
3. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

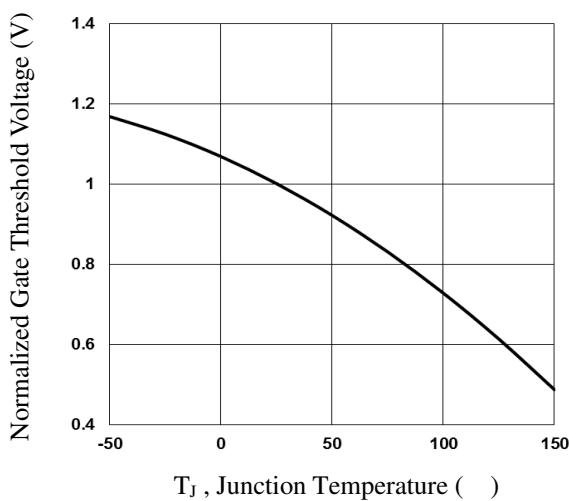
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



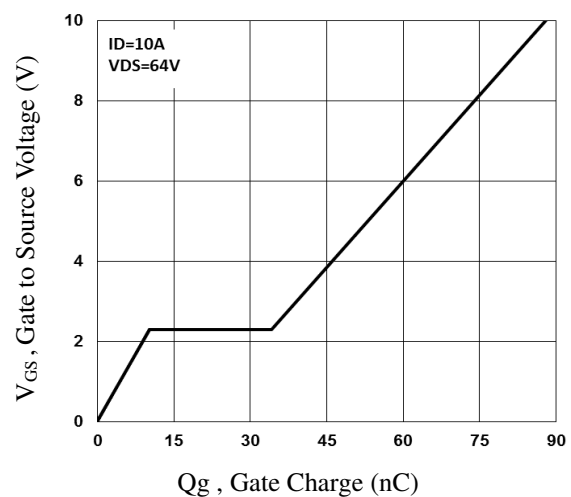
**Fig.1 Continuous Drain Current vs.  $T_C$**



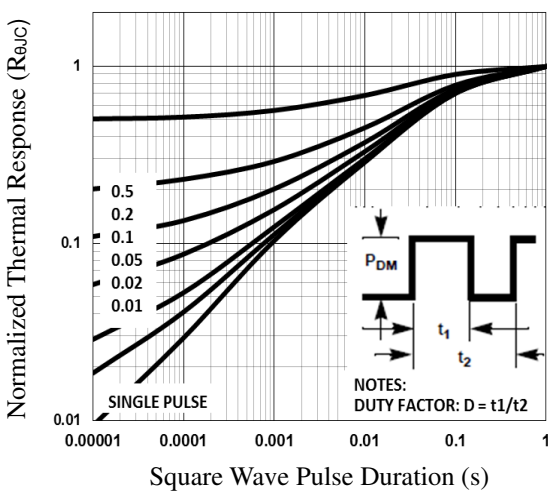
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



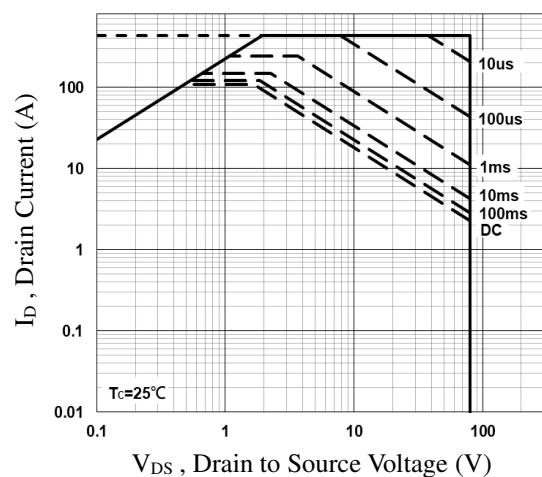
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.4 Gate Charge Characteristics**



**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

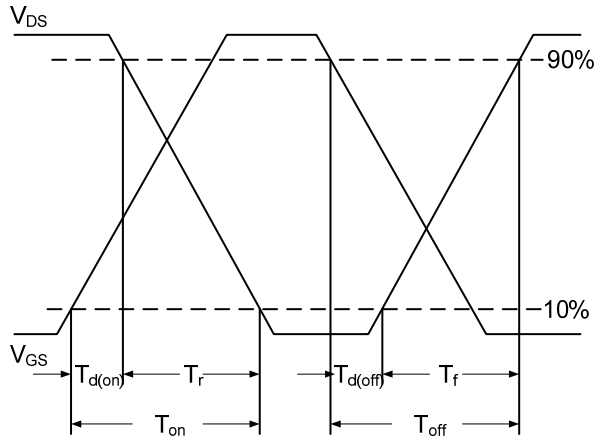


Fig.7 Switching Time Waveform

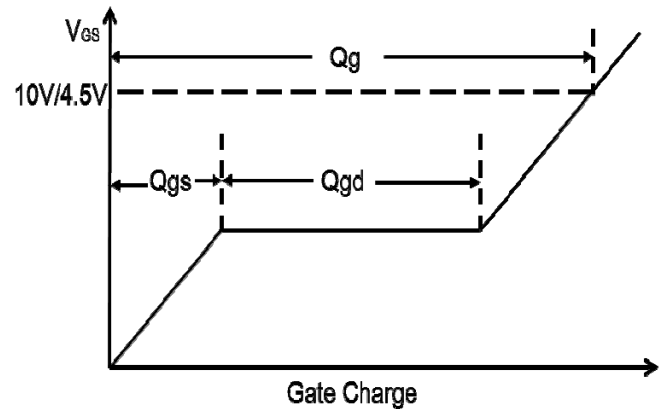
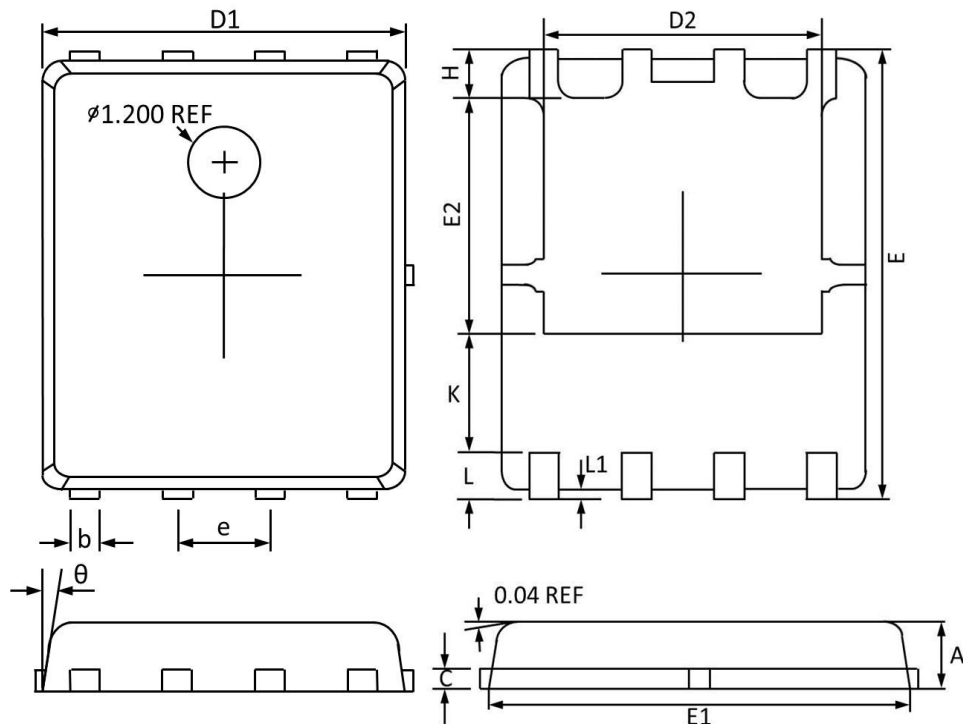


Fig.8 Gate Charge Waveform

## DFN5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
$\theta$	12°	0°	12°	0°